

L Number	Hits	Search Text	DB	Time stamp
1	328552	semiconductor or "integrated circuit"	USPAT; US-PGPUB	2002/05/09 14:46
2	538840	adhesive or encapsulant or resin	USPAT; US-PGPUB	2002/05/09 14:46
3	88893	void or voids	USPAT; US-PGPUB	2002/05/09 14:47
4	6378	(adhesive or encapsulant or resin) with (void or voids)	USPAT; US-PGPUB	2002/05/09 15:10
5	1117	(semiconductor or "integrated circuit") and ((adhesive or encapsulant or resin) with (void or voids))	USPAT; US-PGPUB	2002/05/09 15:10
6	1320828	pressure or vacuum	USPAT; US-PGPUB	2002/05/09 15:10
7	881	((adhesive or encapsulant or resin) with (void or voids)) with (pressure or vacuum)	USPAT; US-PGPUB	2002/05/09 15:11
8	184	((semiconductor or "integrated circuit") and ((adhesive or encapsulant or resin) with (void or voids))) and (((adhesive or encapsulant or resin) with (void or voids)) with (pressure or vacuum))	USPAT; US-PGPUB	2002/05/09 15:11
9	78	((semiconductor or "integrated circuit") and ((adhesive or encapsulant or resin) with (void or voids))) and (((adhesive or encapsulant or resin) with (void or voids)) with (pressure or vacuum))) not (mold or molding)	USPAT; US-PGPUB	2002/05/09 15:12
-	328552	semiconductor or "integrated circuit"	USPAT; US-PGPUB	2002/05/09 14:45
-	538840	adhesive or encapsulant or resin	USPAT; US-PGPUB	2002/05/09 14:46
-	88893	void or voids	USPAT; US-PGPUB	2002/05/09 14:46
-	1036167	heat or heating or heated	USPAT; US-PGPUB	2002/05/09 14:44

Pat Family in STN

Basic Patent (No,Kind,Date): JP 8111470 A2 960430 <No. of Patents: 001>
BGA PACKAGE, MOUNTING BOARD AND SEMICONDUCTOR DEVICE COMPOSED THEREOF (English)

Patent Assignee: TOSHIBA MICRO ELECTRONICS; TOKYO SHIBAURA ELECTRIC CO

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IPC: *H01L-023/12;

Derwent WPI Acc No: *G 96-265834; G 96-265834

Language of Document: Japanese

Patent Family:

Patent No	Kind	Date	Applic No	Kind	Date
JP 8111470	A2	960430	JP 94245238	A	941011 (BASIC)

Priority Data (No,Kind,Date):

JP 94245238 A 941011

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(FILE 'HOME' ENTERED AT 17:52:21 ON 09 MAY 2002)

FILE 'INSPEC' ENTERED AT 17:52:30 ON 09 MAY 2002
E PACKAGING+ALL/CT

L1	1458 E18
L2	20731 VOIDS OR VOID
L3	12 L1 AND L2
L4	13771 RESIN OR ENCAPSULANT
L5	368759 PRESSURE OR VACUUM
L6	5 L1 AND L4 AND L5